

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

1. (original) A method of forming a via hole by firing a laser beam in a resin layer including an inorganic filler, said method of forming a via hole characterized by including:
a first laser beam firing step of firing a laser beam of the infrared region at a position of said resin layer for forming a via hole so as to expel the resin and said inorganic filler and thereby form a hole in said resin layer and
a second laser beam firing step of firing a laser beam of the ultraviolet region focused at a position where said hole is formed to remove a modified layer of the resin remaining at the bottom of said hole and form a via hole with an underlying layer exposed at its bottom.
2. (original) A method of forming a via hole as set forth in claim 1, characterized by:
using a CO₂ laser in the first laser beam firing step and
using a UV-YAG laser in the second laser beam firing step.
3. (original) A method of forming a via hole as set forth in claim 1, characterized in that said resin layer includes at least one type of inorganic filler among barium titanate, titanium oxide, strontium titanate, and barium-strontium titanate.
4. (original) A method of forming a via hole as set forth in claim 1, characterized in that said resin layer includes an inorganic filler with a dielectric constant of 30 to 15000.
5. (original) A method of forming a via hole as set forth in claim 1, characterized in that said resin layer includes an inorganic filler having a band gap of 3 to 4 eV.
6. (new) A method of forming a via hole by firing a laser beam in a resin layer

including an inorganic filler, said method of forming a via hole comprising:

- firing an infrared laser beam at a position of said resin layer;
- expelling the resin and the inorganic filler at the position;
- forming a via hole in the resin layer at the position;
- modifying a layer of the resin remaining at the bottom of the via hole;
- firing an ultraviolet laser beam at the position;
- removing the modified layer of the resin remaining at the bottom of the via hole; and
- exposing an underlying layer at the bottom of the via hole by removing the modified layer of the resin.